

MicroPOWER INSTRUMENTATION AMPLIFIER

Single and Dual Versions

FEATURES

- **LOW QUIESCENT CURRENT:** 175µA/chan.
- **WIDE SUPPLY RANGE:** ±1.35V to ±18V
- **LOW OFFSET VOLTAGE:** 250µV max
- **LOW OFFSET DRIFT:** 3µV/°C max
- **LOW NOISE:** 35nV/√Hz
- **LOW INPUT BIAS CURRENT:** 25nA max
- **8-PIN DIP, SO-8, MSOP-8 SURFACE-MOUNT**
DUAL: 16-Pin DIP, SO-16, SSOP-16

APPLICATIONS

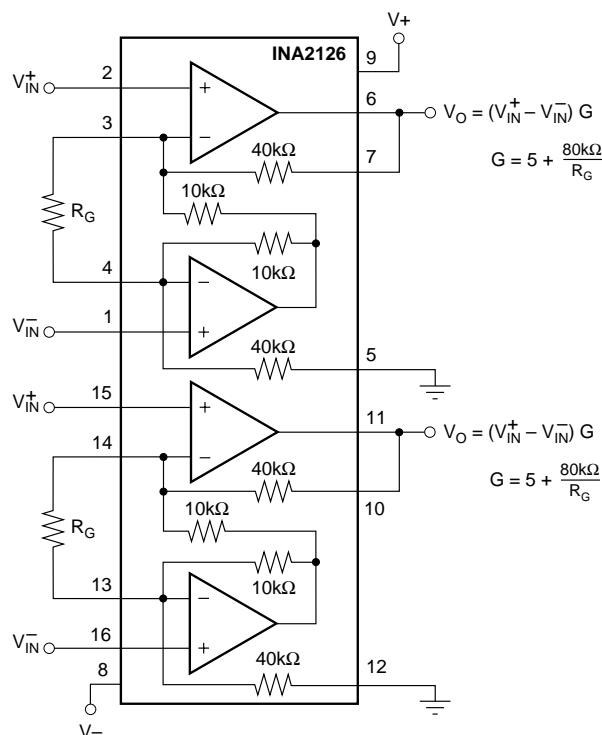
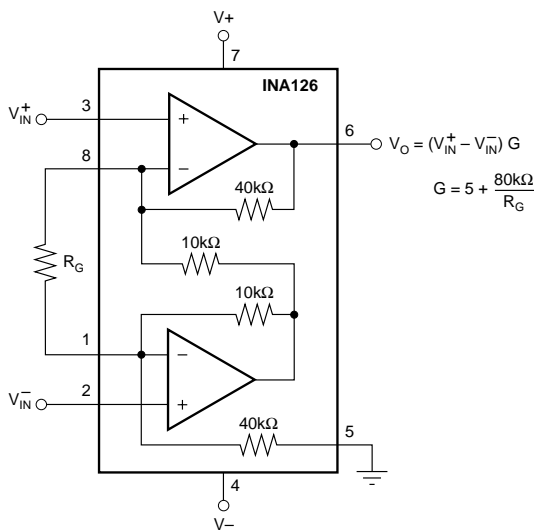
- **INDUSTRIAL SENSOR AMPLIFIER:**
Bridge, RTD, Thermocouple
- **PHYSIOLOGICAL AMPLIFIER:**
ECG, EEG, EMG
- **MULTI-CHANNEL DATA ACQUISITION**
- **PORTABLE, BATTERY OPERATED SYSTEMS**

DESCRIPTION

The INA126 and INA2126 are precision instrumentation amplifiers for accurate, low noise differential signal acquisition. Their two-op-amp design provides excellent performance with very low quiescent current (175µA/channel). This, combined with a wide operating voltage range of ±1.35V to ±18V, makes them ideal for portable instrumentation and data acquisition systems.

Gain can be set from 5V/V to 10000V/V with a single external resistor. Laser trimmed input circuitry provides low offset voltage (250µV max), low offset voltage drift (3µV/°C max) and excellent common-mode rejection.

Single version package options include 8-pin plastic DIP, SO-8 surface mount, and fine-pitch MSOP-8 surface-mount. Dual version is available in the space-saving SSOP-16 fine-pitch surface mount, SO-16, and 16-pin DIP. All are specified for the -40°C to +85°C industrial temperature range.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

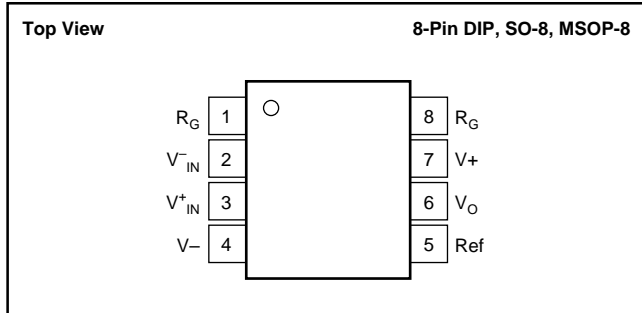
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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

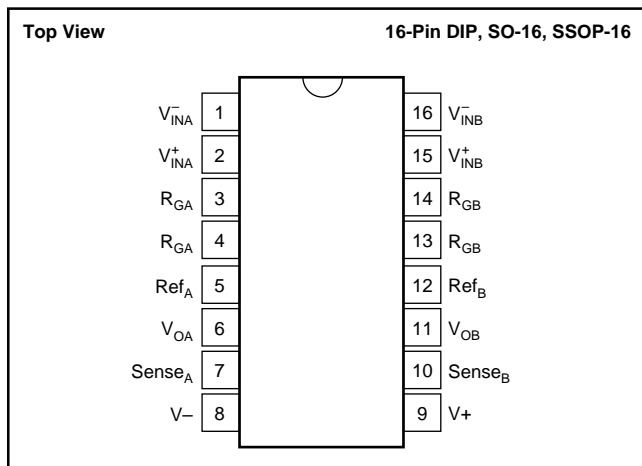
| | |
|---|---|
| Power Supply Voltage, $V+$ to $V-$ | 36V |
| Input Signal Voltage ⁽²⁾ | $(V-)-0.7$ to $(V+)+0.7V$ |
| Input Signal Current ⁽²⁾ | 10mA |
| Output Short Circuit | Continuous |
| Operating Temperature | -55°C to $+125^{\circ}\text{C}$ |
| Storage Temperature | -55°C to $+125^{\circ}\text{C}$ |
| Lead Temperature (soldering, 10s) | $+300^{\circ}\text{C}$ |

NOTES: (1) Stresses above these ratings may cause permanent damage.
 (2) Input signal voltage is limited by internal diodes connected to power supplies. See text.

PIN CONFIGURATION (Single)



PIN CONFIGURATION (Dual)



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

| PRODUCT | PACKAGE-LEAD | PACKAGE MARKING |
|---|------------------------------|--|
| Single | | |
| INA126PA INA126P | DIP-8 DIP-8 | INA126PA INA126P |
| INA126UA INA126U | SO-8 SO-8 | INA126UA INA126U |
| INA126EA ⁽²⁾ " INA126E ⁽²⁾ " | MSOP-8 " MSOP-8 " | A26 ⁽³⁾ " A26 ⁽³⁾ " |
| Dual | | |
| INA2126PA INA2126P | DIP-16 DIP-16 | INA2126PA INA2126P |
| INA2126UA INA2126U | SO-16 SO-16 | INA2126UA INA2126U |
| INA2126EA ⁽²⁾ " INA2126E ⁽²⁾ " | SSOP-16 " SSOP-16 " | INA2126EA " INA2126E " |

NOTES: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com. (2) MSOP-8 and SSOP-16 packages are available only on 250 or 2500 piece reels. (3) Grade designation is marked on reel.

ELECTRICAL CHARACTERISTICS

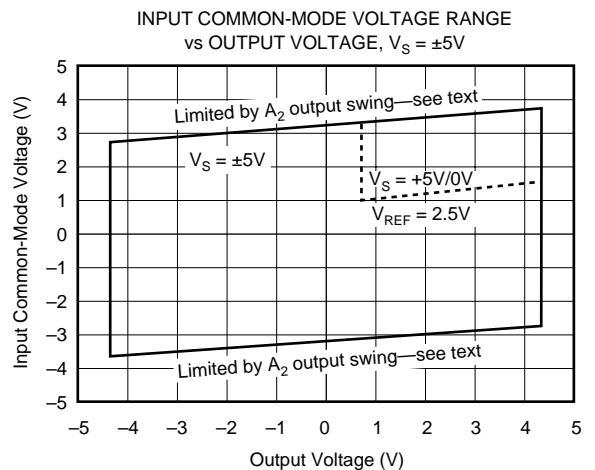
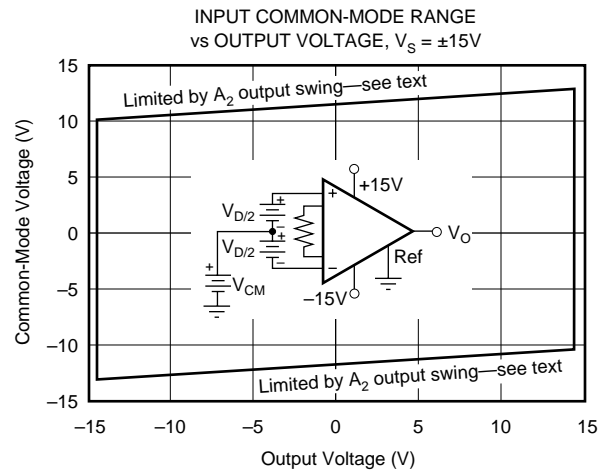
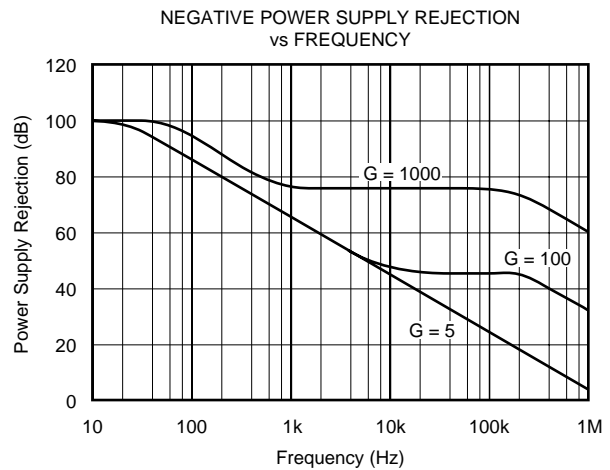
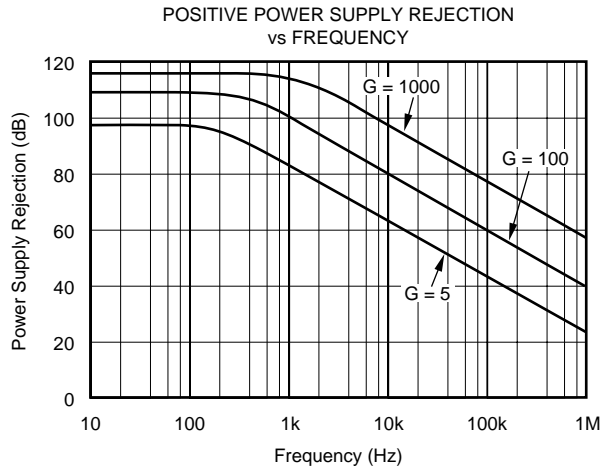
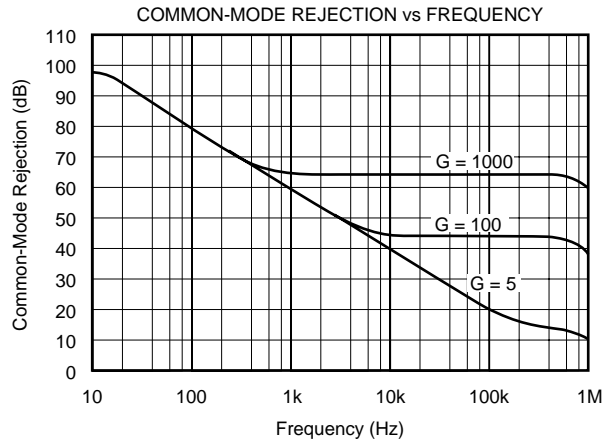
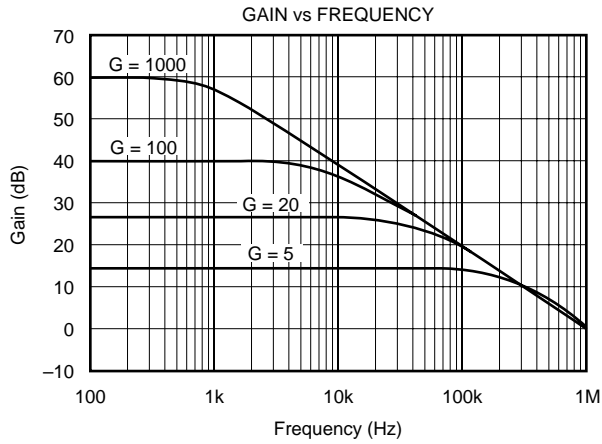
At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, $R_L = 25\text{k}\Omega$, unless otherwise noted.

| PARAMETER | CONDITIONS | INA126P, U, E INA2126P, U, E | | | INA126PA, UA, EA INA2126PA, UA, EA | | | UNITS | |
|--|---|---------------------------------|--------------------------------|--------------|---------------------------------------|-----------|------------|------------------------------|------------------------------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | | |
| INPUT | | | | | | | | | |
| Offset Voltage, RTI vs Temperature | $V_S = \pm 1.35\text{V to } \pm 18\text{V}$ | | ± 100 | ± 250 | | ± 150 | ± 500 | μV | |
| vs Power Supply (PSRR) | | | ± 0.5 | ± 3 | | * | ± 5 | $\mu\text{V}/^\circ\text{C}$ | |
| Input Impedance | | | | 5 | 15 | | * | 50 | $\mu\text{V}/\text{V}$ |
| Safe Input Voltage | | $R_S = 0$ | $(V^-) - 0.5$ | | $(V^+) + 0.5$ | * | | * | $\Omega \parallel \text{pF}$ |
| | $R_S = 1\text{k}\Omega$ | $(V^-) - 10$ | | $(V^+) + 10$ | * | | * | V | |
| Common-Mode Voltage Range | $V_O = 0\text{V}$ | ± 11.25 | ± 11.5 | | * | * | | V | |
| Channel Separation (dual) | $G = 5, \text{dc}$ | | 130 | | | | | dB | |
| Common-Mode Rejection INA2126U (dual SO-16) | $R_S = 0, V_{CM} = \pm 11.25\text{V}$ | 83 | 94 | | 74 | 90 | | dB | |
| | | 80 | 94 | | | | | dB | |
| INPUT BIAS CURRENT | | | | | | | | | |
| vs Temperature | | | -10 | -25 | | * | -50 | nA | |
| Offset Current vs Temperature | | | ± 30 | | | * | | $\text{pA}/^\circ\text{C}$ | |
| | | | ± 0.5 | ± 2 | | * | ± 5 | nA | |
| | | | ± 10 | | | * | | $\text{pA}/^\circ\text{C}$ | |
| GAIN | | | | | | | | | |
| Gain Equation | | | $G = 5 \text{ to } 10\text{k}$ | | | * | | V/V | |
| Gain Error | | | $G = 5 + 80\text{k}\Omega/R_G$ | | | * | | V/V | |
| vs Temperature | $V_O = \pm 14\text{V}, G = 5$ | | ± 0.02 | ± 0.1 | | * | ± 0.18 | % | |
| Gain Error vs Temperature | $G = 5$ | | ± 2 | ± 10 | | * | * | $\text{ppm}/^\circ\text{C}$ | |
| Gain Error vs Temperature | $V_O = \pm 12\text{V}, G = 100$ | | ± 0.2 | ± 0.5 | | * | ± 1 | % | |
| Nonlinearity | $G = 100, V_O = \pm 14\text{V}$ | | ± 25 | ± 100 | | * | * | $\text{ppm}/^\circ\text{C}$ | |
| | | | ± 0.002 | ± 0.012 | | * | * | % | |
| NOISE | | | | | | | | | |
| Voltage Noise, $f = 1\text{kHz}$ | | | 35 | | | * | | $\text{nV}/\sqrt{\text{Hz}}$ | |
| $f = 100\text{Hz}$ | | | 35 | | | * | | $\text{nV}/\sqrt{\text{Hz}}$ | |
| $f = 10\text{Hz}$ | | | 45 | | | * | | $\text{nV}/\sqrt{\text{Hz}}$ | |
| $f_B = 0.1\text{Hz to } 10\text{Hz}$ | | | 0.7 | | | * | | μV_{PP} | |
| Current Noise, $f = 1\text{kHz}$ | | | 60 | | | * | | $\text{fA}/\sqrt{\text{Hz}}$ | |
| $f_B = 0.1\text{Hz to } 10\text{Hz}$ | | | 2 | | | * | | pA_{PP} | |
| OUTPUT | | | | | | | | | |
| Voltage, Positive | $R_L = 25\text{k}\Omega$ | $(V^+) - 0.9$ | $(V^+) - 0.75$ | | * | * | | V | |
| Negative | $R_L = 25\text{k}\Omega$ | $(V^-) + 0.95$ | $(V^-) + 0.8$ | | * | * | | V | |
| Short-Circuit Current | Short-Circuit to Ground | | $+10/-5$ | | | * | | mA | |
| Capacitive Load Drive | | | 1000 | | | * | | pF | |
| FREQUENCY RESPONSE | | | | | | | | | |
| Bandwidth, -3dB | $G = 5$ | | 200 | | | * | | kHz | |
| | $G = 100$ | | 9 | | | * | | kHz | |
| | $G = 500$ | | 1.8 | | | * | | kHz | |
| Slew Rate | $V_O = \pm 10\text{V}, G = 5$ | | 0.4 | | | * | | V/ μs | |
| Settling Time, 0.01% | 10V Step, $G = 5$ | | 30 | | | * | | μs | |
| | 10V Step, $G = 100$ | | 160 | | | * | | μs | |
| | 10V Step, $G = 500$ | | 1500 | | | * | | μs | |
| Overload Recovery | 50% Input Overload | | 4 | | | * | | μs | |
| POWER SUPPLY | | | | | | | | | |
| Voltage Range | | ± 1.35 | ± 15 | ± 18 | * | * | * | V | |
| Current (per channel) | $I_O = 0$ | | ± 175 | ± 200 | | * | * | μA | |
| TEMPERATURE RANGE | | | | | | | | | |
| Specification Range | | -40 | | +85 | * | | * | $^\circ\text{C}$ | |
| Operation Range | | -55 | | +125 | * | | * | $^\circ\text{C}$ | |
| Storage Range | | -55 | | +125 | * | | * | $^\circ\text{C}$ | |
| Thermal Resistance, θ_{JA} | | | | | | | | | |
| 8-Pin DIP | | | 100 | | | * | | $^\circ\text{C}/\text{W}$ | |
| SO-8 Surface-Mount | | | 150 | | | * | | $^\circ\text{C}/\text{W}$ | |
| MSOP-8 Surface-Mount | | | 200 | | | * | | $^\circ\text{C}/\text{W}$ | |
| 16-Pin DIP (dual) | | | 80 | | | * | | $^\circ\text{C}/\text{W}$ | |
| SO-16 (dual) | | | 100 | | | * | | $^\circ\text{C}/\text{W}$ | |
| SSOP-16 (dual) | | | 100 | | | * | | $^\circ\text{C}/\text{W}$ | |

* Specification same as INA126P, INA126U, INA126E; INA2126P, INA2126U, INA2126E.

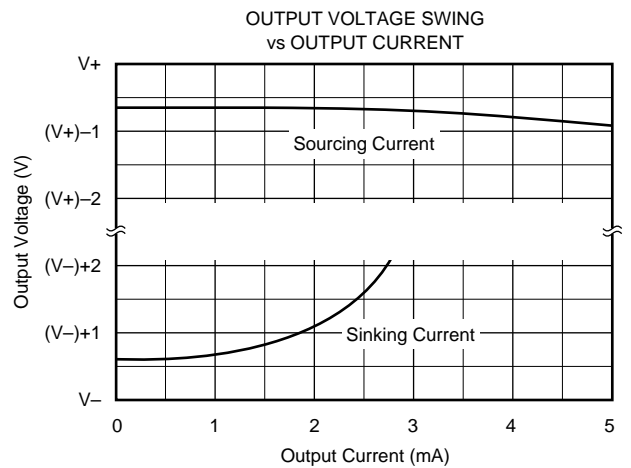
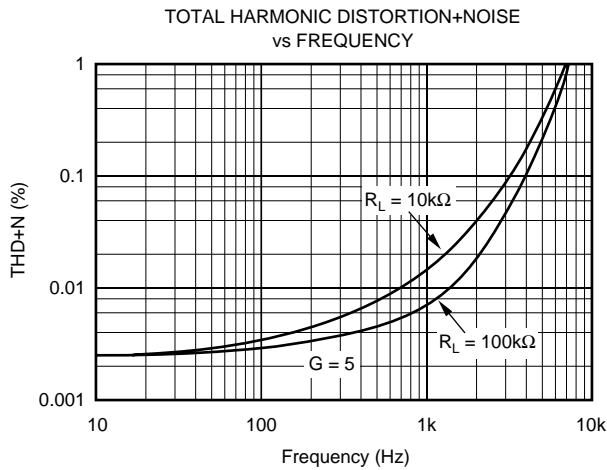
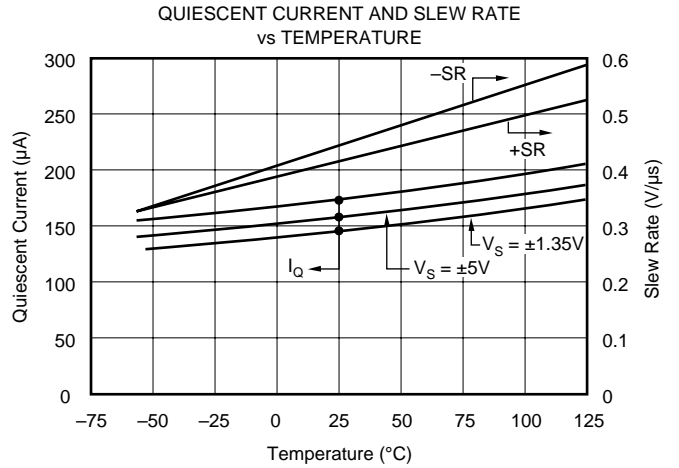
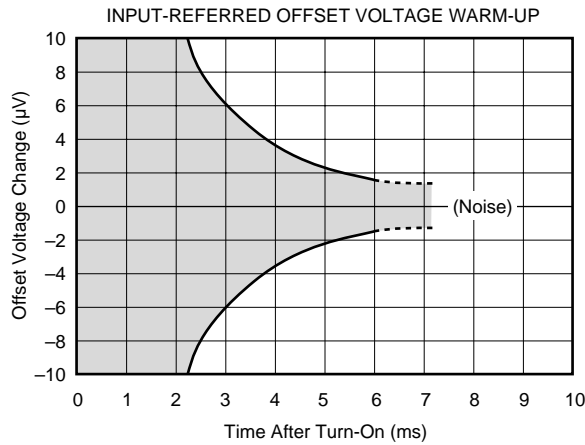
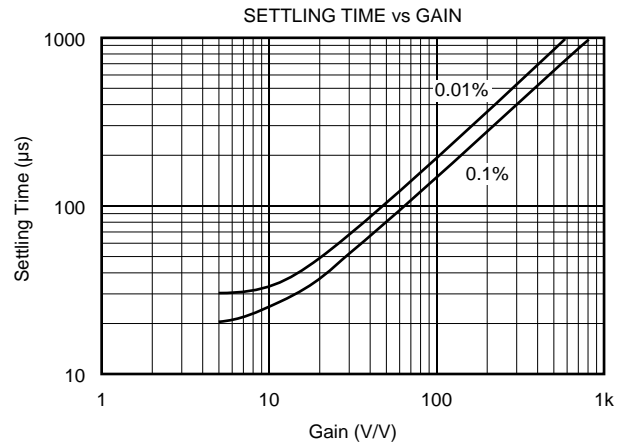
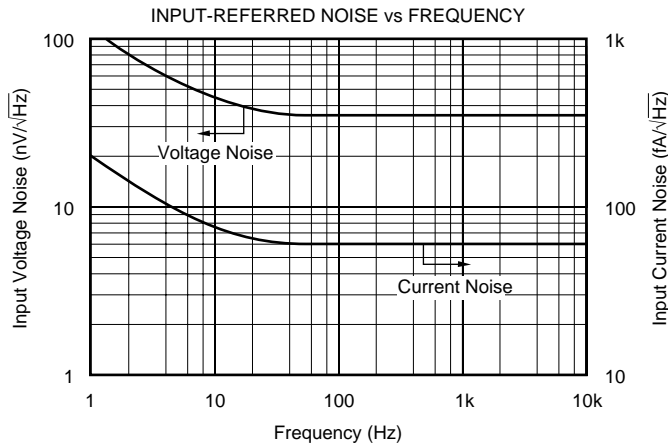
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$ and $V_S = \pm 15\text{V}$, unless otherwise noted.



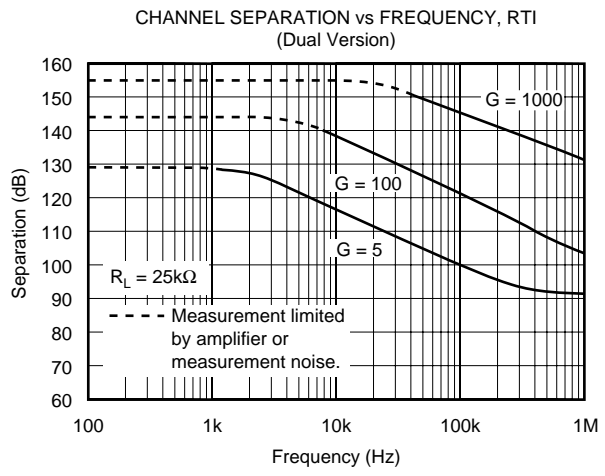
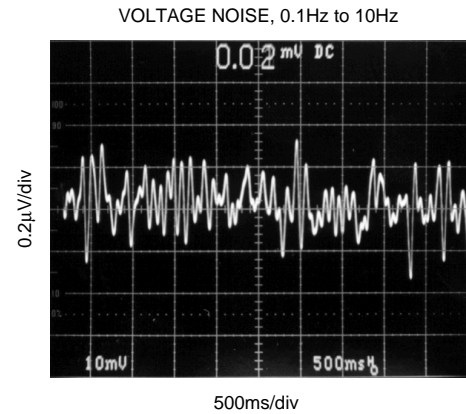
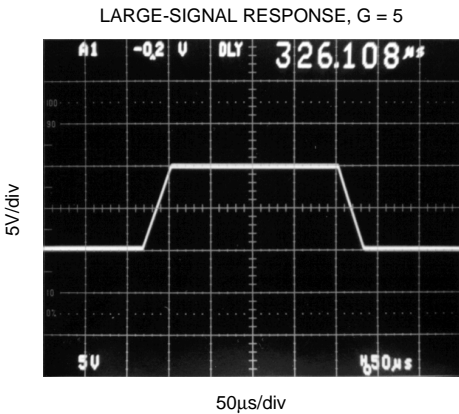
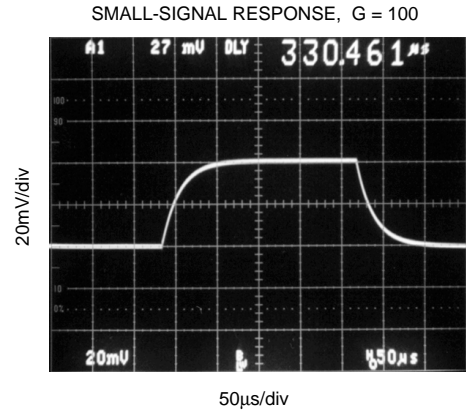
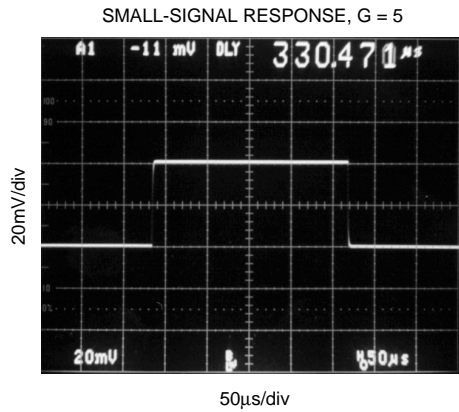
TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$ and $V_S = \pm 15\text{V}$, unless otherwise noted.



TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$ and $V_S = \pm 15\text{V}$, unless otherwise noted.



APPLICATION INFORMATION

Figure 1 shows the basic connections required for operation of the INA126. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminal which is normally grounded. This must be a low-impedance connection to ensure good common-mode rejection. A resistance of 8Ω in series with the Ref pin will cause a typical device to degrade to approximately 80dB CMR.

Dual versions (INA2126) have feedback sense connections, Sense_A and Sense_B. These must be connected to their respective output terminals for proper operation. The sense connection can be used to sense the output voltage directly at the load for best accuracy.

SETTING THE GAIN

Gain is set by connecting an external resistor, R_G, as shown:

$$G = 5 + \frac{80k\Omega}{R_G} \quad (1)$$

Commonly used gains and R_G resistor values are shown in Figure 1.

The 80kΩ term in equation 1 comes from the internal metal film resistors which are laser trimmed to accurate absolute values. The accuracy and temperature coefficient of these resistors are included in the gain accuracy and drift specifications.

The stability and temperature drift of the external gain setting resistor, R_G, also affects gain. R_G's contribution to gain accuracy and drift can be directly inferred from the gain

equation (1). Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance, which will contribute additional gain error in gains of approximately 100 or greater.

OFFSET TRIMMING

The INA126 and INA2126 are laser trimmed for low offset voltage and offset voltage drift. Most applications require no external offset adjustment. Figure 2 shows an optional circuit for trimming the output offset voltage. The voltage applied to the Ref terminal is added to the output signal. An op amp buffer is used to provide low impedance at the Ref terminal to preserve good common-mode rejection.

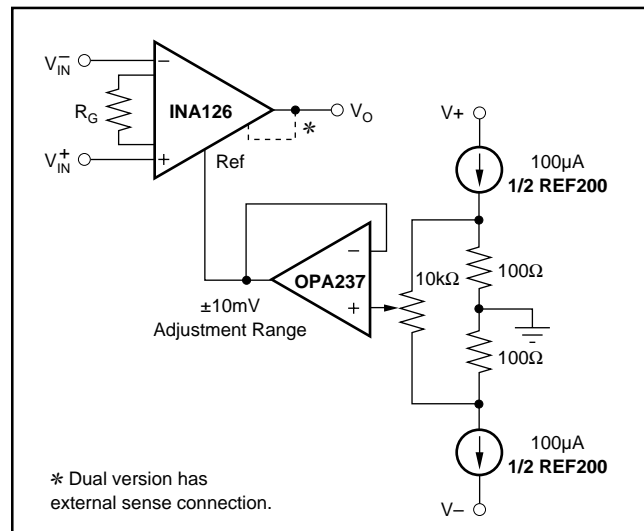


FIGURE 2. Optional Trimming of Output Offset Voltage.

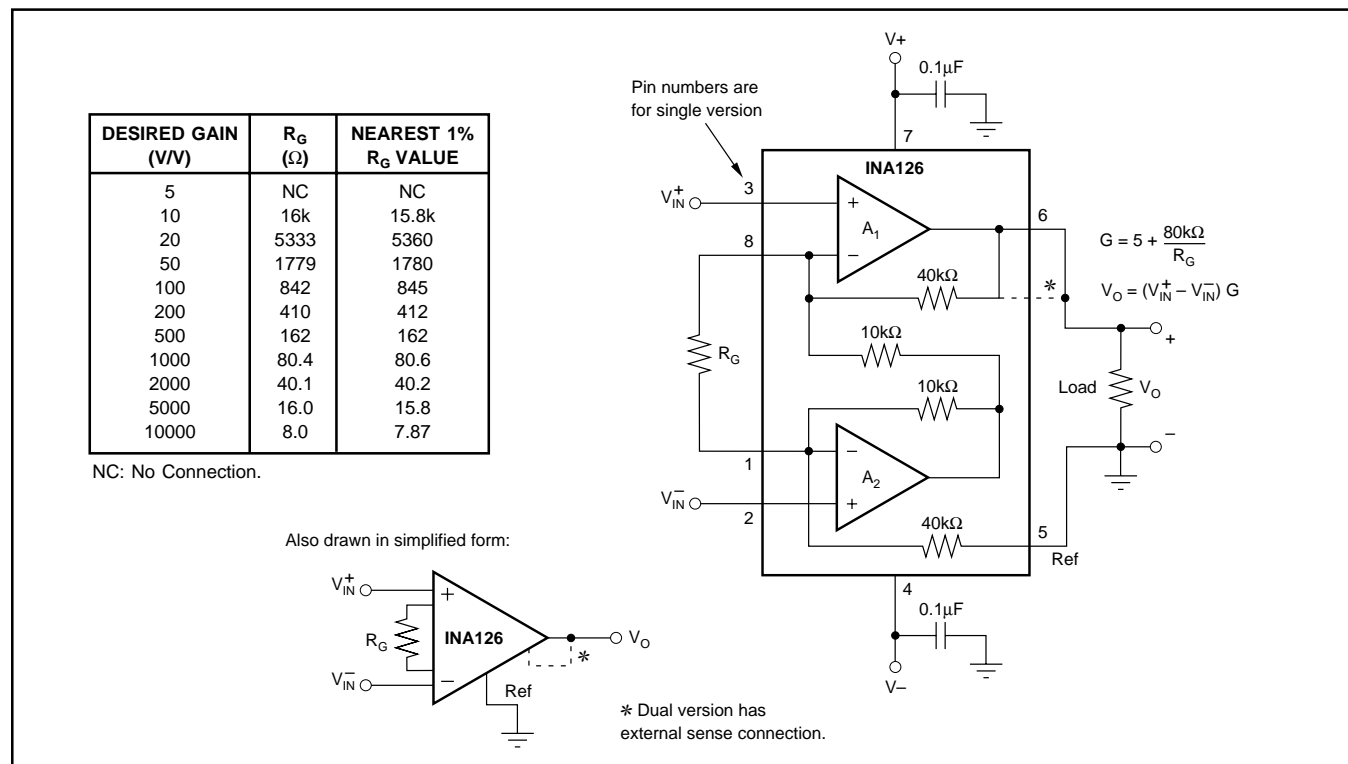


FIGURE 1. Basic Connections.

INPUT BIAS CURRENT RETURN

The input impedance of the INA126/2126 is extremely high—approximately $10^9\Omega$. However, a path must be provided for the input bias current of both inputs. This input bias current is typically -10nA (current flows out of the input terminals). High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current for proper operation. Figure 3 shows various provisions for an input bias current path. Without a bias current path, the inputs will float to a potential which exceeds the common-mode range and the input amplifiers will saturate.

If the differential source resistance is low, the bias current return path can be connected to one input (see the thermocouple example in Figure 3). With higher source impedance, using two equal resistors provides a balanced input with advantages of lower input offset voltage due to bias current and better high-frequency common-mode rejection.

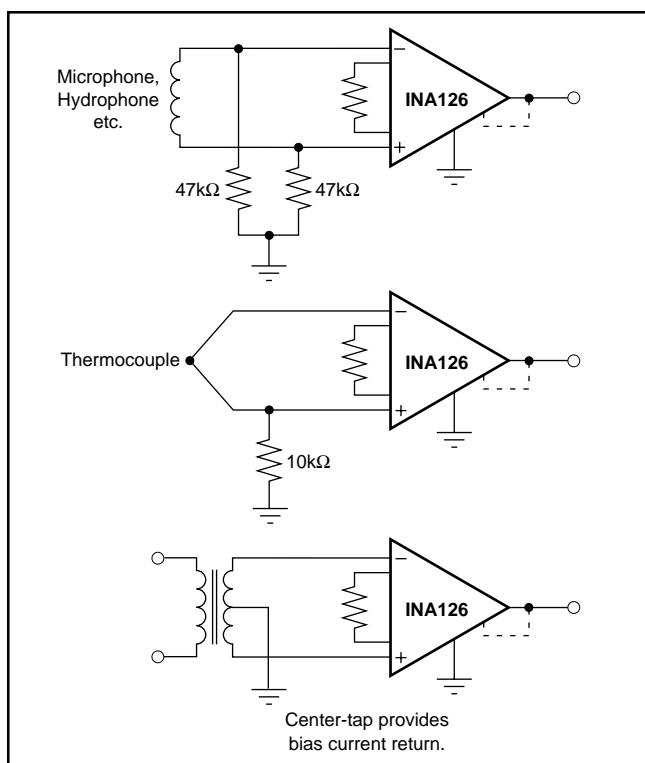


FIGURE 3. Providing an Input Common-Mode Current Path.

INPUT COMMON-MODE RANGE

The input common-mode range of the INA126/2126 is shown in the typical characteristic curves. The common-mode range is limited on the negative side by the output voltage swing of A_2 , an internal circuit node that cannot be measured on an external pin. The output voltage of A_2 can be expressed as:

$$V_{O2} = 1.25 V_{IN}^- - (V_{IN}^+ - V_{IN}^-) (10\text{k}\Omega/R_G) \quad (2)$$

(Voltages referred to Ref terminal, pin 5)

The internal op amp A_2 is identical to A_1 and its output swing is limited to typically 0.7V from the supply rails. When the input common-mode range is exceeded (A_2 's output is saturated), A_1 can still be in linear operation and respond to changes in the non-inverting input voltage. The output voltage, however, will be invalid.

LOW VOLTAGE OPERATION

The INA126/2126 can be operated on power supplies as low as $\pm 1.35\text{V}$. Performance remains excellent with power supplies ranging from $\pm 1.35\text{V}$ to $\pm 18\text{V}$. Most parameters vary only slightly throughout this supply voltage range—see typical characteristic curves. Operation at very low supply voltage requires careful attention to ensure that the common-mode voltage remains within its linear range. See “Input Common-Mode Voltage Range.”

The INA126/2126 can be operated from a single power supply with careful attention to input common-mode range, output voltage swing of both op amps and the voltage applied to the Ref terminal. Figure 4 shows a bridge amplifier circuit operated from a single $+5\text{V}$ power supply. The bridge provides an input common-mode voltage near 2.5V , with a relatively small differential voltage.

INPUT PROTECTION

The inputs are protected with internal diodes connected to the power supply rails. These diodes will clamp the applied signal to prevent it from exceeding the power supplies by more than approximately 0.7V . If the signal source voltage can exceed the power supplies, the source current should be limited to less than 10mA . This can generally be done with a series resistor. Some signal sources are inherently current-limited and do not require limiting resistors.

CHANNEL CROSSTALK—DUAL VERSION

The two channels of the INA2126 are completely independent, including all bias circuitry. At DC and low frequency there is virtually no signal coupling between channels. Crosstalk increases with frequency and is dependent on circuit gain, source impedance and signal characteristics.

As source impedance increases, careful circuit layout will help achieve lowest channel crosstalk. Most crosstalk is produced by capacitive coupling of signals from one channel to the input section of the other channel. To minimize coupling, separate the input traces as far as practical from any signals associated with the opposite channel. A grounded guard trace surrounding the inputs helps reduce stray coupling between channels. Carefully balance the stray capacitance of each input to ground, and run the differential inputs of each channel parallel to each other, or directly adjacent on top and bottom side of a circuit board. Stray coupling then tends to produce a common-mode signal that is rejected by the IA's input.

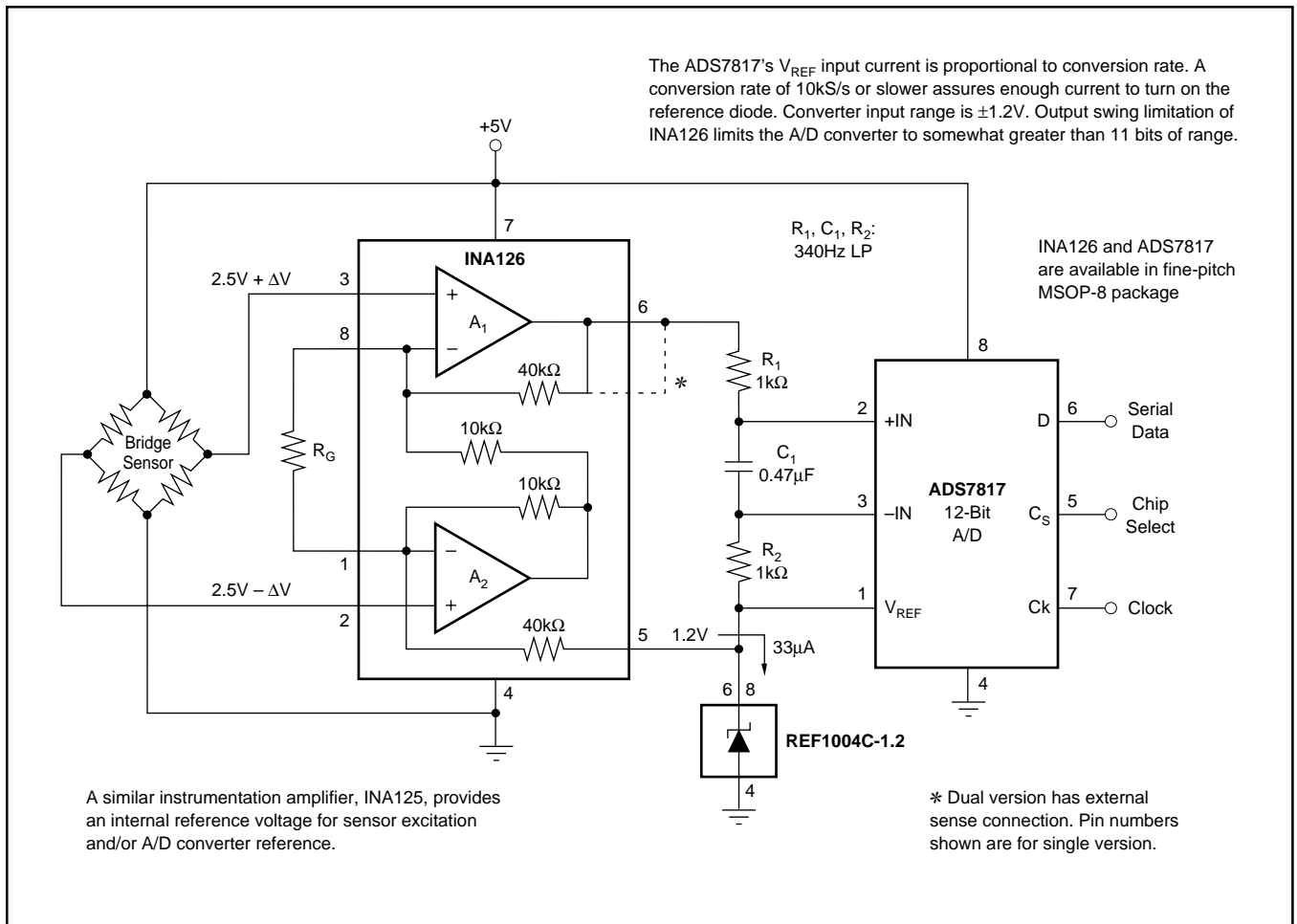


FIGURE 4. Bridge Signal Acquisition—Single 5V Supply.

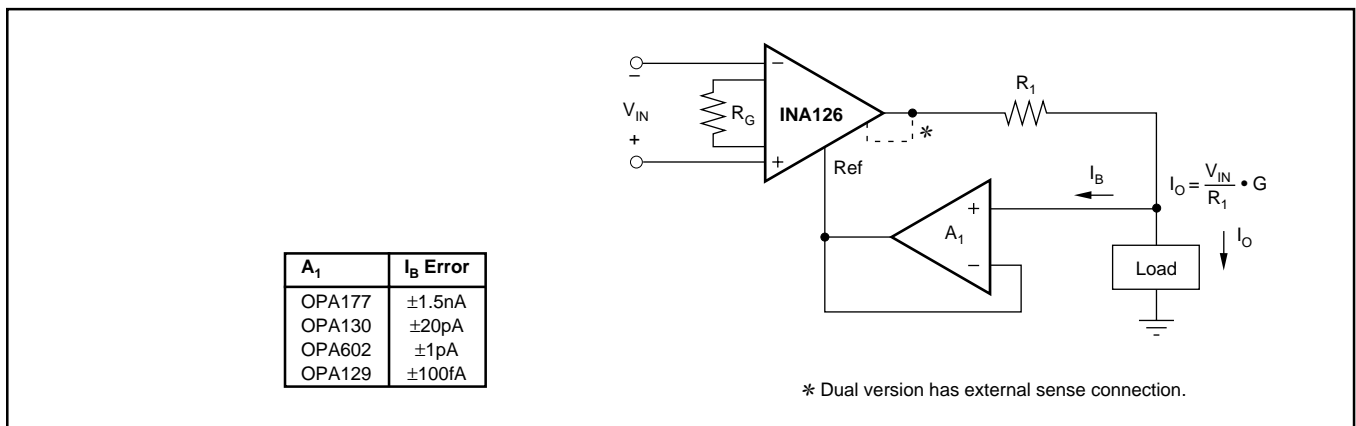


FIGURE 5. Differential Voltage-to-Current Converter.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| INA126E/250 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126E/250G4 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126E/2K5 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126E/2K5G4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126EA/250 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126EA/250G4 | ACTIVE | VSSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126EA/2K5 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126EA/2K5G4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | | A26 | Samples |
| INA126P | ACTIVE | PDIP | P | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA126P | Samples |
| INA126PA | ACTIVE | PDIP | P | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA126P A | Samples |
| INA126PAG4 | ACTIVE | PDIP | P | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA126P A | Samples |
| INA126PG4 | ACTIVE | PDIP | P | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA126P | Samples |
| INA126U | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U | Samples |
| INA126U/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U | Samples |
| INA126U/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U | Samples |
| INA126UA | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| INA126UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U A | Samples |
| INA126UA/2K5E4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U A | Samples |
| INA126UAG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U A | Samples |
| INA126UG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA 126U | Samples |
| INA2126E/250 | ACTIVE | SSOP | DBQ | 16 | 250 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126E/250G4 | ACTIVE | SSOP | DBQ | 16 | 250 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126E/2K5 | ACTIVE | SSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126E/2K5G4 | ACTIVE | SSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126EA/250 | ACTIVE | SSOP | DBQ | 16 | 250 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126EA/250G4 | ACTIVE | SSOP | DBQ | 16 | 250 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126EA/2K5 | ACTIVE | SSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126EA/2K5G4 | ACTIVE | SSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | Call TI | Level-3-260C-168 HR | | INA 2126E A | Samples |
| INA2126P | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA2126P | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| INA2126PA | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA2126P A | Samples |
| INA2126PAG4 | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA2126P A | Samples |
| INA2126PG4 | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type | | INA2126P | Samples |
| INA2126U | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2126U | Samples |
| INA2126UA | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |
| INA2126UA/2K5 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |
| INA2126UA/2K5E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |
| INA2126UAE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |
| INA2126UAG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |
| INA2126UE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2126U | Samples |
| SN200501036DRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2126U A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| INA126E/250 | VSSOP | DGK | 8 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| INA126EA/250 | VSSOP | DGK | 8 | 250 | 180.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| INA126UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| INA2126UA/2K5 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| INA126E/250 | VSSOP | DGK | 8 | 250 | 210.0 | 185.0 | 35.0 |
| INA126EA/250 | VSSOP | DGK | 8 | 250 | 210.0 | 185.0 | 35.0 |
| INA126UA/2K5 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| INA2126UA/2K5 | SOIC | D | 16 | 2500 | 367.0 | 367.0 | 38.0 |

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4073329/E 05/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

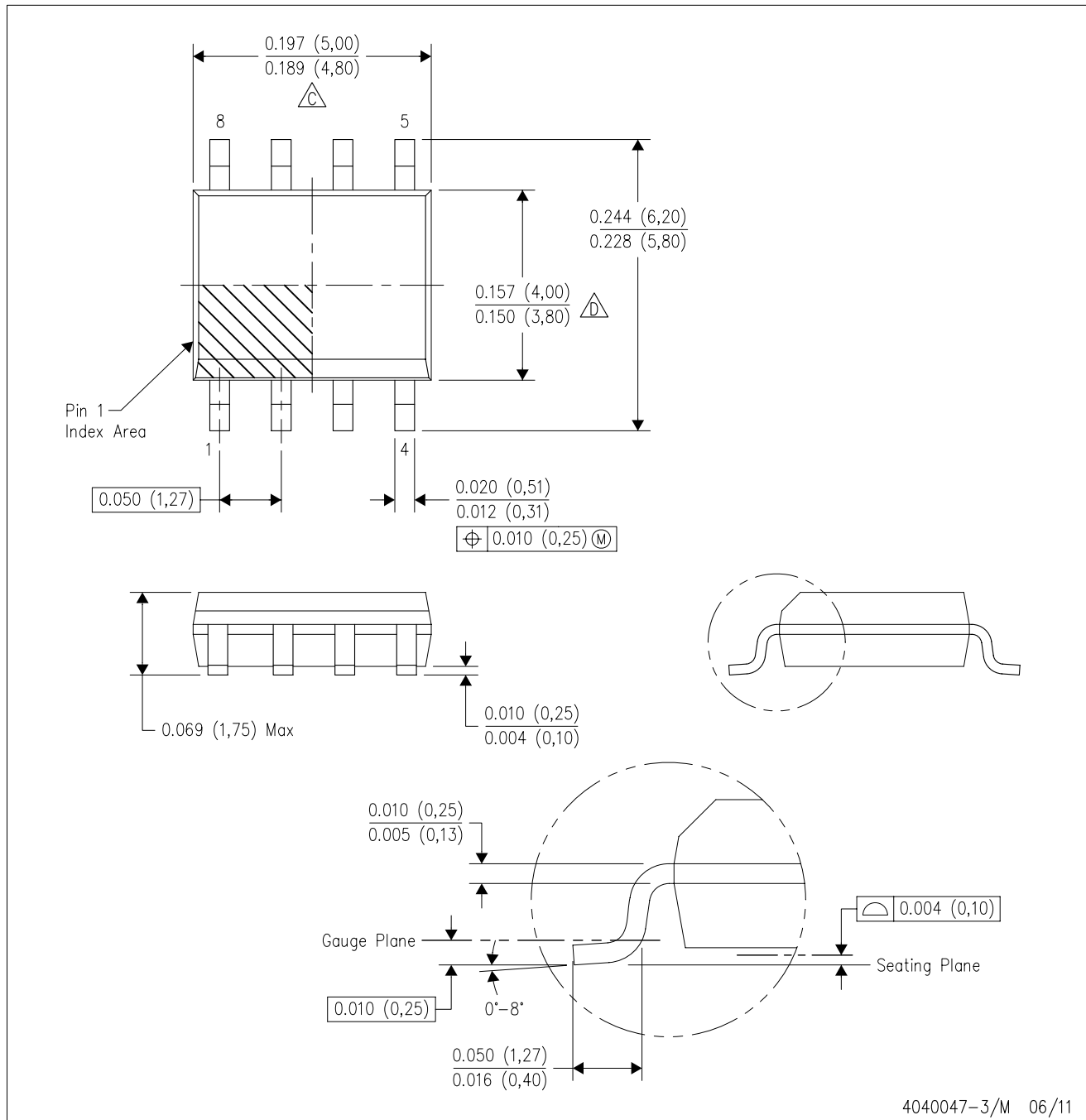
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

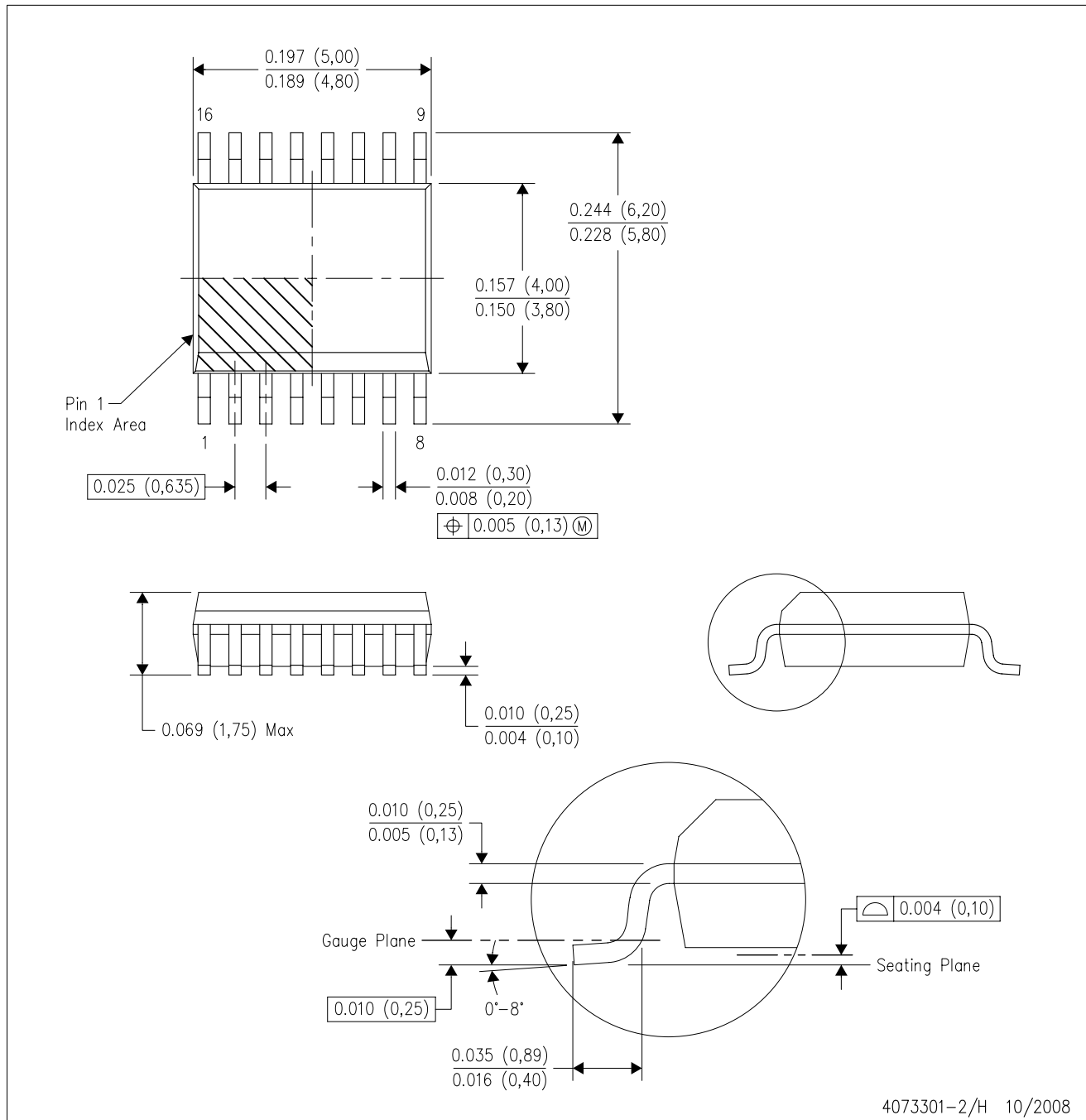
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DBQ (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AB.

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